White Paper:

Usage of D6T-44L / D6T-8L Thermal sensor
1. Outline

This application note provides a supplement to the data sheet for D6T series non-contact temperature sensor – by adding special instructions and usage information.

*Please see Omron’s website for the most current datasheet.

2. Structure

The D6T series sensors are made up of a cap with silicon lens, MEMS thermopile sensor chips, and dedicated analog circuit and a logic circuit for converting to a digital temperature value on a single board through one connector.

![Module outline (Reference)](Fig1.1)

3. Dimensions

Please refer to the data sheet for complete dimension details. The height of the lens on the D6T-44L and D6T-8L are different, but both feature a small PCB (14mm x 18mm). The module also has a retention area and holes usable for proper alignment. For connector details please see Section 6.

4. Operating principle

An outline of the basic measuring operation is as follows:

- The silicon lens collects radiated heat (far-infrared ray) emitted from an object onto the thermopile sensor in the module.

- The radiated heat (far-infrared ray) produces an electromotive force on the thermopile sensor.

- The analog circuit calculates the temperature of an object by using the electromotive force value and a measured temperature value inside the module.

- The measured value is outputted through an I2C bus.

![Module construction](Fig4.1)
5. Features

The non-contact temperature sensor measures the surface temperature of an object. D6T-44L-06 and D6T-8L-06 have sensor chip arrays of 16 channels (4x4) and 8 channels (1x8) respectively. By mounting the signal processing circuit closely to the sensor chip, a low noise temperature measurement is realized.

The module can also be used for detecting the presence of human beings. Omron’s non-contact temperature sensor can solve the shortcomings of a conventional pyroelectric sensor, which cannot catch the signal of a stationary person because the sensor detects the change of signal [in principle]. Moreover, Omron’s non-contact temperature sensor keeps detecting the far-infrared ray of an object, while the pyroelectric models do not.

![Fig 5.1 Difference between pyroelectric and non-contact temperature sensors](image)

(a) Pyroelectric sensor output  (b) Non-contact temperature sensor output

The non-contact temperature sensor achieves its sensitivity characteristic for an object view angle by using a silicon lens. FOV (Field Of View) – an indication of view angle – is generally specified as an area angle of 50% for maximum sensitivity.
Please note that the sensitivity area is wider than the FOV specified area. When an object to be measured is smaller than the sensitivity area, the background temperature effects the measurements.

Though Omron's D6T sensor corrects a temperature measurement value by using a reference heat source (blackbody furnace), the measurement's value is influenced by the emissivity of the specific material of the object to be measured, and the surface shape of the occupant relative to the sensitivity area.

**Fig 5.2 Sensitivity characteristics: FOV Image**

Note: The occupied area in FOV becomes smaller with increasing distance and the background temperature prevails.
In cases where a D6T sensor is used for detecting human beings, the application will be limited to close range when the detection programming scheme only judges by temperature value. To extend the detection distance, improvements to the judgment accuracy can be made via software programming, considering time change, heat source location and human being movement.

6. Usage

6.1 Connector

![Connector outline](image)

**Fig 6.1 Connector outline**

<table>
<thead>
<tr>
<th>Connector pin</th>
<th>Table 6.1 Pin</th>
</tr>
</thead>
<tbody>
<tr>
<td>1 GND</td>
<td>Ground</td>
</tr>
<tr>
<td>2 VCC</td>
<td>Power source (5V +/-10%)</td>
</tr>
<tr>
<td>3 SDA</td>
<td>I2C(5V) Data line</td>
</tr>
<tr>
<td>4 SCL</td>
<td>I2C(5V) Clock line</td>
</tr>
</tbody>
</table>

One Connector (used inside sensor) : JST p/n SM04B-GHS-TB
To connect to the system, use the following four-pin mating connector.

Contact : JST p/n SSHL-002T-P0.2 (4pcs).
Housing : JST p/n GHR-04V-S

The difference in appearance is due to the varying height of the lens. For detailed dimensions, please refer to the data sheet.
6.2 Electrical connection

Case 1: Direct connection. The voltage of MCU Power source is 5V.

![Direct connection diagram](image)

**Fig 6.2(a) Direct connection**

Case 2: Direct connection. 3V MCU (5V-tolerant I2C port)

![5V-tolerant diagram](image)

**Fig 6.2(b) 5V-tolerant**

Case 3: Using I2C level translating IC.
(not 5V-tolerant, other LV-devices exist on the same I2C-bus)

![Using I2C level translating IC](image)

**Fig 6.2(c) Using I2C level translating IC**
Pull-Up Resistor:

Impedance value is decided by user. (see I2C[100kHz] specification note.)
(Most case: About 3k to 10k ohm)

Case 4: Software I2C. using Bi-directional Open Drain GPIO ports.
(MCU has no I2C module inside.)

Note: Wait routine for Clock-Stretching is required – to be prepared by the user.

![Figure 6.2(d) Using GPIO-ports](image)

Case 5: Using I2C bus switch IC. Ex. PCA9545(4ch), PCA9548(8ch)
(multiple D6T sensors)

![Figure 6.2(e) Using I2C bus switch IC](image)
6.3 I2C port setting

Table 6.2  I2C port parameters

<table>
<thead>
<tr>
<th>Device Address</th>
<th>7bit: 0001_010b</th>
</tr>
</thead>
<tbody>
<tr>
<td>8bit (with R/W bit)</td>
<td>Read: 15h, Write: 14h</td>
</tr>
<tr>
<td>Data bit width</td>
<td>8bit (MSB-first)</td>
</tr>
<tr>
<td>Clock Frequency</td>
<td>max 100kHz</td>
</tr>
<tr>
<td>Control for Clock-stretching</td>
<td>On (Auto waiting) *see Section 6.6</td>
</tr>
</tbody>
</table>

Table 6.3  Output data format

<table>
<thead>
<tr>
<th>PTAT</th>
<th>The value of the reference temperature, inside the sensor module. Temperature data (PTAT&amp;Pn) is 16bit-width, signed, 10 times value of degC. Example: 12.7 °C = 007Fh(127) , 25.8 °C = 0102Fh(258)</th>
</tr>
</thead>
<tbody>
<tr>
<td>P0 to P15 (D6T-44L)</td>
<td>Measured value. Pixel order is below.</td>
</tr>
<tr>
<td>P0 to P7 (D6T-8L)</td>
<td></td>
</tr>
<tr>
<td>PEC</td>
<td>Packet error check code. Based on the “SM bus” specification.</td>
</tr>
</tbody>
</table>
Case 8ch (D6T-8L)

Case 16ch (D6T-44L)

For each term, please see the I2C specification.
6.4 Example Getting the measurement value. (16ch : D6T-44L)

```c
extern void I2C_start();
extern void I2C_repeatstart();
extern void I2C_stop();
extern void I2C_send1(char addr8, char cmd);
extern void I2C_getx(char addr8, char buff[], int length);
extern int D6T_checkPEC(char buf, int pPEC);

// Global var.
extern char readbuff[35];
extern int tPTAT;
extern int tP[16];
extern int tPEC;

int D6T_getvalue()
{
    I2C_start();
    I2C_send1(0x14, 0x04); // 14h = { 0Ah(Addr7) : Write(0b) }
    I2C_repeatstart();
    I2C_getx(0x15, readbuff, 35); // 15h = { 0Ah(Addr7) : Read }, 35 = 2*(1+16)+1
    I2C_stop();
    if(!D6T_checkPEC(readbuff, 34))
    {
        return -1; // error
    }
    tPTAT = 256*readbuff[1] + readbuff[0];
    tP[0] = 256*readbuff[3] + readbuff[2];
    tP[8] = 256*readbuff[19] + readbuff[18];
    tP[10] = 256*readbuff[23] + readbuff[22];
    tP[12] = 256*readbuff[27] + readbuff[26];
    tP[13] = 256*readbuff[29] + readbuff[28];
    tP[14] = 256*readbuff[31] + readbuff[30];
    tPEC = readbuff[34];
    return 1;
}

measure()
{
    n = 0;
    do{
        status = D6T_getvalue();
        n++;
    }while(status < 0 && n < LOOPLIMIT);
    if(status < 0){
        // error operation.
    }
    printf("%d, %d,%d,%d,%d %d,%d,%d,%d,%d,%d,%d,%d,%d,%d,%d,%d\n",
            tPTAT, tP[0], tP[1], tP[2], tP[3], tP[4], tP[5], tP[6], tP[7],
            tP[8], tP[9], tP[10], tP[11], tP[12], tP[13], tP[14], tP[15], tPEC);
}
```
Note. The I2C operation library function used here is composed only of standard features.
If you want to try, please use the library functions similar to that provided by the MCU vendor.

Output Example (PTAT, P0, P1, ..., P15, PEC)

223, 224, 224, 273, 335, 239, 221, 240, 297, 264, 232, 221, 254, 299, 258, 229, 233, 80


223, 296, 273, 285, 311, 306, 291, 281, 301, 311, 310, 293, 296, 312, 322, 311, 302, 83

PTAT=22.3 °C, P0=29.6 °C, P1=27.3 °C, P2=28.5 °C ...

Modification example (8ch : D6T-8L)

```c
int D6T_getvalue()
{
    I2C_start();
    I2C_send1( 0x14 , 0x4C ); // 14h = { 0Ah(Addr7) : Write(0b) }
    I2C_repeatstart();
    I2C_getx( 0x15 , readbuff , 19 ); // 15h = { 0Ah(Addr7):Read },19 = 2*(1+8)+1
    I2C_stop();
    If(!D6T_checkPEC(readbuff,18)){
        return -1; // error
    }
    tPTAT = 256*readbuff[1] + readbuff[0];
    tP[0] = 256*readbuff[3] + readbuff[2];
    tPEC = readbuff[18];
    return 1;
}
```
Note. This example represents a single measurement run. This sensor repeats the operation for each of the data measurements and updates within 250ms. Therefore, you will be able to retrieve new data about 4 times per second. It is not possible for the user to control the measurement timing.

6.5 PEC check routine Example

PEC is the data used for the CRC-8 error checking method; it is then appended to the end of the communication output. It allows you to detect communication failures effectively and improve the reliability of the data. (For more information, please refer to the SMBus specification)

```c
unsigned char calc_crc(unsigned char data)
{
    int index;
    unsigned char temp;

    for(index=0;index<8;index++)
    {
        temp = data;
        data <<= 1;
        if(temp & 0x80) data ^= 0x07;
    }

    return data;
}

int D6T_checkPEC(char buf, int pPEC)
{
    unsigned char crc;
    int i;

    crc = calc_crc(0x14);
    crc = calc_crc(0x4C ^ crc);
    crc = calc_crc(0x15 ^ crc);
    for(i=0;i<pPEC;i++)
    {
        crc = calc_crc(readbuff[i] ^ crc);
    }

    return (crc == readbuff[pPEC]);
}
```

Other case: Using Stop-Start condition without Repeat Start Condition,

```c
int D6T_checkPEC(char buf, int pPEC)
{
    unsigned char crc;
    int i;

    crc = calc_crc(0x15);
    for(i=0;i<pPEC;i++)
    {
        crc = calc_crc(readbuff[i] ^ crc);
    }

    return (crc == readbuff[pPEC]);
}
```

6.6 Detect routine of wait status (Clock-stretching)

Our sensor may require a wait request of the master. On the master side, it is necessary to deal with
this wait process. In many I2C modules in the MCU, there is a feature that can do this automatically. However, if using the I2C software library, the user may have to deal with this wait process manually.

<table>
<thead>
<tr>
<th>I2C Master</th>
<th>I2C Slave(D6T)</th>
</tr>
</thead>
<tbody>
<tr>
<td>a) SCL drive to Lo for Ack.</td>
<td>Checking SCL status.(Lo)</td>
</tr>
<tr>
<td>c) SCL output change to Hi-Z.</td>
<td>b) SCL drive to Lo for Wait.</td>
</tr>
<tr>
<td>SCL I/O mode change to Input</td>
<td>Wait ...</td>
</tr>
<tr>
<td>d) Checking SCL status.(Hi)</td>
<td></td>
</tr>
<tr>
<td></td>
<td>e) SCL output change to Hi-Z.</td>
</tr>
<tr>
<td></td>
<td>f) Finish Detected.</td>
</tr>
<tr>
<td></td>
<td>g) Next operation.</td>
</tr>
</tbody>
</table>

6.7 Temperature range
A: D6T-44L-06/D6T-8L-06 Recommended detection range.
B: Maximum ratings.
C: Ability range (out of ratings, for reference)
The temperature range of some of the electronic components is from 0 to 85° C, however, the operating temperature range of the module is limited to 0 to 50 ° C with a detection range as shown in the above diagram, figure 6.5. Note: Temperature range is subject to change, please confirm with the latest product specification information.
6.8 Cover Material

If you opt to put a cover over the sensor, carefully consider the performance of the material in regards to how well it passes through radiant heat. High-density polyethylene (HDPE, grade far infrared transmission) is a good cover material option. If the cover is thick, the transmittance decreases. It is best to use as thin a cover as possible to keep a minimal impact on detection performance. The internal sensors can then show through. (as shown in the example pictured below).

```
<table>
<thead>
<tr>
<th>None cover</th>
<th>HDPE (t0.7)</th>
<th>HDPE (t0.5)</th>
<th>HDPE (t0.3)</th>
</tr>
</thead>
<tbody>
<tr>
<td>100%</td>
<td>54.9%</td>
<td>60.1%</td>
<td>71.5%</td>
</tr>
</tbody>
</table>
```

Fig 6.6 HDPE thickness vs. Transmittance (reference)
## 7. FAQ

<table>
<thead>
<tr>
<th>Question</th>
<th>Answer</th>
</tr>
</thead>
<tbody>
<tr>
<td>Can the field of view (FOV) angle be increased?</td>
<td>No. OMRON set the FOV in consideration of the constraints imposed by the thickness and refractive index of the silicon lens. Measurement distance is reduced as the FOV of one element increases. Therefore, we cannot simply widen the viewing angle. A good way to measure a wide range is to install multiple sensors, or mount the sensor on a movable/rotating base.</td>
</tr>
<tr>
<td>Are there any effects on an infrared remote controller?</td>
<td>No. The silicon lens we are using will not pass through most near-infrared and visible light below 1.2 ([\mu\text{m}]) wavelength. Therefore, it does not affect the infrared signal of the remote controller. The far infrared rays that are emitted as radiant heat are about 4 to 14 ([\mu\text{m}]).</td>
</tr>
<tr>
<td>Is it possible to distinguish between humans, animals, and appliances?</td>
<td>No. In the non-contact temperature module, you can only acquire surface temperature measurement data. Different objects of the same temperature will read the same. Further discrimination must be based on the behavior of the measured data to distinguish the object by software on the user side. By developing software designed with your specific application in mind, the determination accuracy may possibly be improved.</td>
</tr>
<tr>
<td>What is the distance range that can detect the presence of people?</td>
<td>This is greatly affected by the decision performance and software installation conditions. It is also affected by the size of the object to be measured and the area of the FOV per element. A rough guideline distance is about 5 to 6 meters.</td>
</tr>
<tr>
<td>Can the power consumption be reduced?</td>
<td>No. The D6T thermal sensor does not have a power saving mode. Therefore, in order to reduce power consumption it is necessary to shut off the power.</td>
</tr>
<tr>
<td>Is there a sensor that can operate on a supply voltage of 3([\text{V}])?</td>
<td>Is there an I2C slave address that I can change?</td>
</tr>
<tr>
<td></td>
<td>No. The D6T thermal sensor not support them.</td>
</tr>
</tbody>
</table>
8. Terms

- **Thermopile**
  Thermal sensors utilize the Seebeck effect in which thermoelectric force is generated due to the temperature difference at the contact points between two different kinds of metal. A thermopile is created by serially connecting thermocouples. By creating hot junctions on highly heat-resistant dielectric membranes, and cold junctions on highly heat-conductive silicon, it is possible to achieve high-speed response and high-energy conversion efficiency.

- **NETD**
  Noise Equivalent Temperature Difference.
  An indication of the amount of noise that is expressed as a temperature. It becomes a measure of the minimum value of the change in the measured temperature that can be determined. It is sometimes referred to as temperature resolution.

- **FOV**
  Field of View. FOV range is often defined in the range 50% of the peak sensitivity.

I2C is a registered trademark of Philips.
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  ➢ **Americas Sales Office**
  

  ➢ **Mail Contact**
  
  components@omron.com

  ➢ **Phone**
  
  Tel: (847) 882-2288
  Fax: (847) 882-2192
  55 Commerce Drive, Schaumburg, IL 60173  USA

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